



Procurement and Contracting Services

Request for Proposals for a Wafer Dicing Saw

Addendum 1

**Please mark all proposal submission
Files with the following information**

**Sealed RFP # S192522
Due on June 5, 2025 no later than 2:00 PM, MST**

The following questions were received prior to the technical question period close of May 22, 2025 at 12:00PM MST. The University's responses are provided below:

1. Wafer Final Application

- a. What is the intended use or application scenario for the wafers?
 - i. Mostly it will be to dice silicon wafers, fused silica, GaAs, SiO₂. Samples will range in dimension from small (2-3 mm samples) to 300 mm silicon wafers. Dicing dimensions are sometimes as small as 1mm between cuts.

2. Wafer Specifications

- a. Size (diameter): ranges from small, 2-3 mm rhomboidal shapes, to full 300mm wafers.
- b. Thickness. Thickness will not exceed 800microns
- c. Material. Silicon, fused silica, GaAs, SiO₂
- d. Die size: Can be as small as 1mmx2mm.
- e. Cutting street width: not applicable. Blade width is typically 50um.

3. Design Files

- a. Do you have any 2D or 3D wafer drawings available? no
- b. Preferred formats: .dwg / .dxf (2D) or .stp (3D)
- c. These files will be used to run a sample test and provide you with cutting results for evaluation.

4. Cutting Requirement

- a. Appearance expectations (e.g., chipping on top/bottom sides, burrs, scratches), and the microscope magnification used for inspection
- b. Dimensional precision and post-cut size tolerance
- c. Taper requirement, if any
- d. Strength or breakage resistance standards
- e. Whether wafers will undergo any post-cut etching processes
 - i. No spec requirements for this category.

5. Is it ok that I fill in the questions, explanations on spec requests (including references) and sign this attachment and return in total? Yes.

6. I have two models of 300mm saws available. One is single spindle DAD3361 the other has two spindles DAD3661. Would you like a quote for both or only one? A quote for both would be most excellent.

7. It says only 2 uploads are allowed, I assume the attachment that was sent and my quote?

Documents, quotes, required certifications, etc., should be combined into one file if possible.

End of Addendum, all else remains the same.